### HMPS-2822

# RF/Microwave mixer/detector diode

### Description



Lifecycle status: Active



#### **Features**

The MiniPak HMPS-282x family of Schottky diodes is the most consistent and best all-round device available, and finds applications in mixing, detecting, switching, sampling, clamping and wave shaping at frequencies up to 6 GHz. The MiniPak package offers reduced parasitics when compared to conventional leaded diodes, and lower thermal resistance. VBR=15 V, Ct=1.0pF, RD=10 Ohms, Vf @ 1 mA=340 mV

# HSMS-282x

# Surface Mount RF Schottky Barrier Diodes



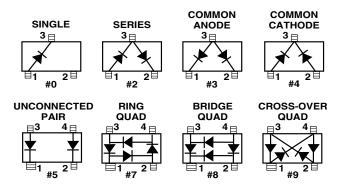
# **Data Sheet**

### **Description/Applications**

These Schottky diodes are specifically designed for both analog and digital applications. This series offers a wide range of specifications and package configurations to give the designer wide flexibility. Typical applications of these Schottky diodes are mixing, detecting, switching, sampling, clamping, and wave shaping. The HSMS-282x series of diodes is the best all-around choice for most applications, featuring low series resistance, low forward voltage at all current levels and good RF characteristics.

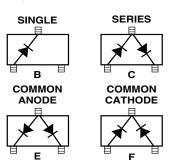
Note that Avago's manufacturing techniques assure that dice found in pairs and quads are taken from adjacent sites on the wafer, assuring the highest degree of match.

# Package Lead Code Identification, SOT-23/SOT-143 (Top View)



### Package Lead Code Identification, SOT-323

### (Top View)

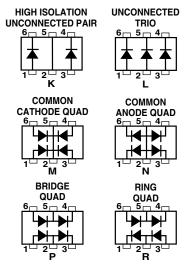


#### **Features**

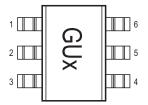
- Low Turn-On Voltage (As Low as 0.34 V at 1 mA)
- Low FIT (Failure in Time) Rate\*
- Six-sigma Quality Level
- Single, Dual and Quad Versions
- Unique Configurations in Surface Mount SOT-363 Package
  - increase flexibility
  - save board space
  - reduce cost
- HSMS-282K Grounded Center Leads Provide up to 10 dB Higher Isolation
- Matched Diodes for Consistent Performance
- Better Thermal Conductivity for Higher Power Dissipation
- Lead-free Option Available
- For more information see the Surface Mount Schottky Reliability Data Sheet.

### Package Lead Code Identification, SOT-363

### (Top View)



# **Pin Connections and Package Marking**



#### Notes:

- 1. Package marking provides orientation and identification.
- 2. See "Electrical Specifications" for appropriate package marking.

# Absolute Maximum Ratings<sup>[1]</sup> T<sub>c</sub> = 25°C

Symbol	Parameter	Unit	SOT-23/SOT-143	SOT-323/SOT-363
I <sub>f</sub>	Forward Current (1 µs Pulse)	Amp	1	1
P <sub>IV</sub>	Peak Inverse Voltage	V	15	15
T <sub>j</sub>	Junction Temperature	°C	150	150
T <sub>stg</sub>	Storage Temperature	°C	-65 to 150	-65 to 150
$\theta_{jc}$	Thermal Resistance <sup>[2]</sup>	°C/W	500	150

#### Notes:

- 1. Operation in excess of any one of these conditions may result in permanent damage to the device.
- 2.  $T_c = +25^{\circ}$ C, where  $T_c$  is defined to be the temperature at the package pins where contact is made to the circuit board.

# Electrical Specifications T<sub>c</sub> = 25°C, Single Diode<sup>[3]</sup>

Part Number HSMS <sup>[4]</sup>	Package Marking Code	Lead Code	Configuration	Minimum Breakdown Voltage V <sub>BR</sub> (V)	Maximum Forward Voltage V <sub>F</sub> (mV)	Maximum Forward Voltage V <sub>F</sub> (V) @ I <sub>F</sub> (mA)	Maximum Reverse Leakage I <sub>R</sub> (nA) @ V <sub>R</sub> (V)	Maximum Capacitance C <sub>T</sub> (pF)	Typical Dynamic Resistance R <sub>D</sub> (Ω) <sup>[5]</sup>
2820	C0	0	Single	15	340	0.5 10	100 1	1.0	12
2822	C2	2	Series						
2823	C3	3	Common Anode						
2824	C4	4	Common Cathode						
2825	C5	5	Unconnected Pair						
2827	C7	7	Ring Quad <sup>[4]</sup>						
2828	C8	8	Bridge Quad <sup>[4]</sup>						
2829	C9	9	Cross-over Quad						
282B	C0	В	Single						
282C	C2	C	Series						
282E	C3	E	Common Anode						
282F	C4	F	Common Cathode						
282K	CK	K	High Isolation Unconnected Pair						
282L	CL	L	Unconnected Trio						
282M	HH	M	Common Cathode Quad						
282N	NN	N	Common Anode Quad						
282P	CP	Р	Bridge Quad						
282R	00	R	Ring Quad						
Test Cor	nditions			$I_R = 100 \mu A$	$I_F = 1 \text{ mA}^{[1]}$			$V_{R} = 0V^{[2]}$ f = 1 MHz	$I_F = 5 \text{ mA}$

#### Notes:

- 1.  $\Delta \rm V_{\rm F}$  for diodes in pairs and quads in 15 mV maximum at 1 mA.
- 2.  $\Delta C_{\tau o}$  for diodes in pairs and quads is 0.2 pF maximum.
- 3. Effective Carrier Lifetime ( $\tau$ ) for all these diodes is 100 ps maximum measured with Krakauer method at 5 mA.
- 4. See section titled "Quad Capacitance."
- 5.  $R_D = R_S + 5.2\Omega$  at 25°C and  $I_f = 5$  mA.

### **Diode Burnout**

Any Schottky junction, be it an RF diode or the gate of a MESFET, is relatively delicate and can be burned out with excessive RF power. Many crystal video receivers used in RFID (tag) applications find themselves in poorly controlled environments where high power sources may be present. Examples are the areas around airport and FAA radars, nearby ham radio operators, the vicinity of a broadcast band transmitter, etc. In such environments, the Schottky diodes of the receiver can be protected by a device known as a limiter diode. [5] Formerly available only in radar warning receivers and other high cost electronic warfare applications, these diodes have been adapted to commercial and consumer circuits.

Avago offers a complete line of surface mountable PIN limiter diodes. Most notably, our HSMP-4820 (SOT-23) can act as a very fast (nanosecond) power-sensitive switch when placed between the antenna and the Schottky diode, shorting out the RF circuit temporarily and reflecting the excessive RF energy back out the antenna.

[5] Avago Application Note 1050, "Low Cost, Surface Mount Power Limiters."

### **Assembly Instructions**

### **SOT-3x3 PCB Footprint**

Recommended PCB pad layouts for the miniature SOT-3x3 (SC-70) packages are shown in Figures 26 and 27 (dimensions are in inches). These layouts provide ample allowance for package placement by automated assembly equipment without adding parasitics that could impair the performance.

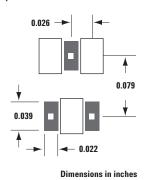


Figure 26. Recommended PCB Pad Layout for Avago's SC70 3L/SOT-323 Products.

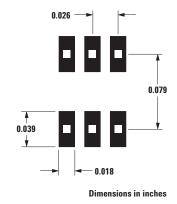
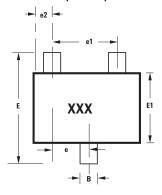
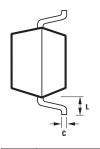


Figure 27. Recommended PCB Pad Layout for Avago's SC70 6L/SOT-363 Products.

# **Package Dimensions**

# Outline 23 (SOT-23)



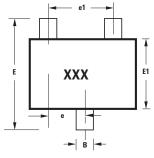


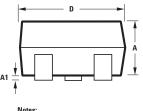
ŀ	D	
		A
<b>†</b>		Î
A1 <u>†</u>		

Notes: XXX-package marking Drawings are not to scale

	DIMENSIONS (mm)		
SYMBOL	MIN.	MAX.	
Α	0.79	1.20	
A1	0.000	0.100	
В	0.37	0.54	
С	0.086	0.152	
D	2.73	3.13	
E1	1.15	1.50	
е	0.89	1.02	
e1	1.78	2.04	
e2	0.45	0.60	
E	2.10	2.70	
L	0.45	0.69	

# Outline SOT-323 (SC-70 3 Lead)

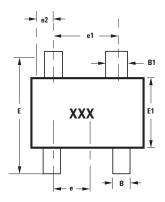


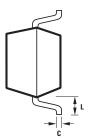


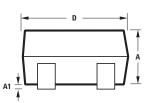
Notes:	
XXX-package marking	
Drawings are not to scale	

	DIMENSIONS (mm)			
SYMBOL	MIN.	MAX.		
Α	0.80	1.00		
A1	0.00	0.10		
В	0.15	0.40		
С	0.10	0.20		
D	1.80	2.25		
E1	1.10	1.40		
е	0.65 typical			
e1	1.30 typical			
E	1.80	2.40		
L	0.425 typical			

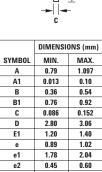
# Outline 143 (SOT-143)







Notes: XXX-package marking Drawings are not to scale



0.45

2.10

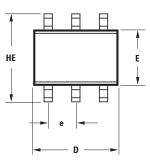
0.45

E

0.60

2.65

# Outline SOT-363 (SC-70 6 Lead)



A1		A2	A
<b>†</b> -	b		

	DIMENSIONS (mm)		
SYMBOL	MIN.	MAX.	
E	1.15	1.35	
D	1.80	2.25	
HE	1.80	2.40	
Α	0.80	1.10	
A2	0.80	1.00	
A1	0.00	0.10	
Q1	0.10	0.40	
е	0.650 BCS		
b	0.15	0.30	
С	0.10	0.20	
1	0.10	0.30	

